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제품 소개 Product Description

당사는 Pb free Solder제품 종합 업체로서 기존 납솔더의 사용으로 인한 환경오염 문제를 해소한 환경 친화형 Pb Free EF Solder제품 및 할로겐프리 Cream, Bar, Wire, BGA Ball 및 Preform Solder 전제품을 생산, 판매하고 있습니다.

Our company is a specialized Pb free Solder Products. Our main products are all forms of environment friendly Pb Free EF Solder Products, Halogen Free Products such as Cream, Bar, Wire, BGA Ball and Preform Solder products that solve a problem of environment pollution by using the existing Pb solder.

EF SOLDER



EF SOLDER CREAM

EF SOLDER BAR

EF SOLDER WIRE

EF SOLDER Preform

EF SOLDER BALL

EF SOLDER BGA Flux

EF SOLDER Bumping

EF Paste Conductive Paste

합금 조성표 Solder Alloy Composition

품명 Product No.	합금성분 Solder Composition	용 점 Melting point (°C)		형 상 Form				
		고상점 Solidus	액상점 Liquidus	Cream	Bar	Wire	Ball	Preform
3C30	Sn3Cu(α)	227	312		○			
3C40	Sn4Cu(α)	227	353		○			
4S40	Sn4Sb2.5Cu(α)	232	312		○	○		
2C07	Sn0.7Cu(α)	227	227		○	○		
3N06S	Sn0.5Cu0.06Ni(α)	220	229		○	○		
2N06	Sn0.06Ni(α)	230	233		○	○		
2A30	Sn3Ag(α)	217	220		○	○		
3A10	Sn1.0Ag0.5Cu	221	225	○	○	○		○
3A03	Sn0.3Ag0.7Cu	221	227	○	○	○		
4A03	Sn0.3Ag0.7Cu(α)	221	227		○	○		
2A35	Sn3.5Ag	221	221	○	○	○	○	
2S50	Sn5Sb	232	240	○	○	○		○
3C05	Sn3Ag0.5Cu(α)	217	217	○	○	○	○	○
5C05	Sn3Ag0.5Cu($\alpha\beta$)	217	217	○	○	○		
5A35	Sn3.5Ag0.5Cu(Ni,Ge)	217	217	○	○	○		
3Z80	Sn8Zn3Bi	191	191	○	○			
4B10	Sn2.5Ag0.4Cu1Bi	214	221	○	○			
4B20	Sn2.5Ag0.4Cu2Bi	215	216	○	○		○	
4B30	Sn2.5Ag0.4Cu3Bi	214	216	○	○			
4B40	Sn2.5Ag0.4Cu4Bi	210	213	○	○			
4I20	Sn2.5Ag3Bi2In	195	204	○				
2B58	Sn58Bi(1Ag)	139	139	○				

* 상기 조성 Solder 제품과 사용 용도에 따라 사양의 Solder 제품을 주문 생산 · 공급하고 있습니다.



제품 특징 Product Features

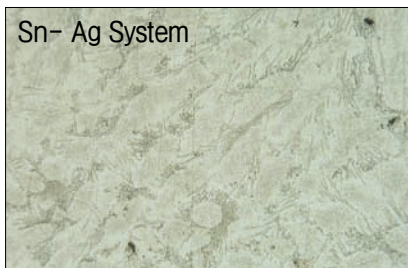
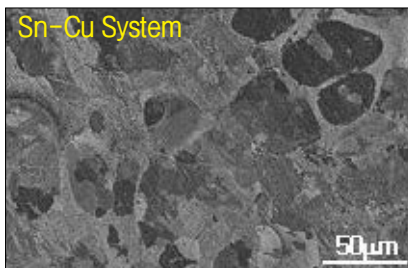
(주)에코조인은 고청정 · 고품질 솔더합금, 분말, 플럭스의 개발에 의해 저산소, 균질화된 양질의 친환경 Pb Free EF 솔더 제품을 제조, 공급하고 있습니다.

Ecojoin Co., Ltd. manufactures and supplies low oxide, homogenized excellent environment friendly Pb Free EF Solder products through the development of ultra clean, high quality solder alloy, powder and flux.

솔더 합금 특징 Features of Solder Alloy

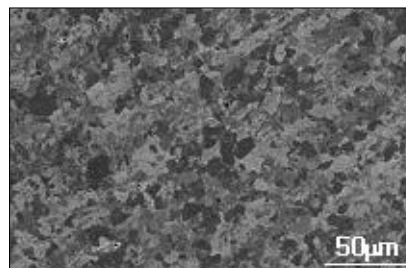
- ▶ 고청정 고품질
- ▶ 극저산소 함유
- ▶ 성분이 균질
- ▶ Ultra Clean High Quality
- ▶ Containing extremely low oxygen
- ▶ Homogenized component

Traditional Pb Free Solder Alloy



Alloy elements: heterogeneity
Oxygen content: over 20 ppm

New Melting Process

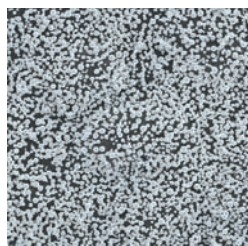
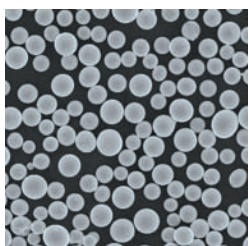
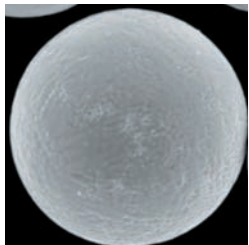


Alloy elements: homogeneity
Oxygen content: under 5 ppm

분말 특징 Powder Features

- ▶ 성분균질
- ▶ 산소 함유량 극소
- ▶ 균일한 Powder 형상 및 입도
- ▶ Homogenized component
- ▶ Extremely low oxygen content
- ▶ Homogenous Powder shape & Granularity

① 입도 및 형상 (Granularity and Shape)

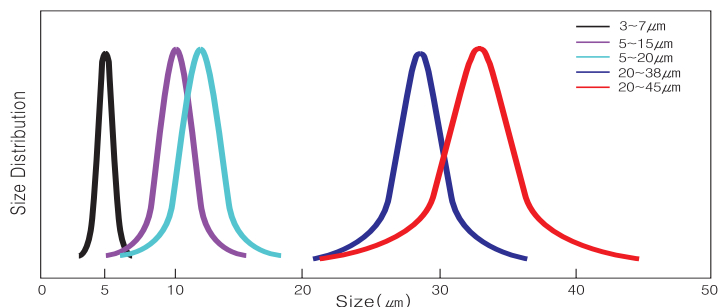


(a) For Printing

(b) For Bumping

① 입도 분포도(Distribution of Granularity)

구 분(Classification)	Size(μm)
For Printing	20~45
	20~38
	20~32
For Bumping	5~20
	5~15
	3~7



Pb Free EF Solder Cream Series

- ▶ Void 발생 극소
- ▶ 고 신뢰성
- ▶ 할로겐 프리, 무세정, 무악취의 친환경형
- ▶ 범용실장부터 Micro Bump까지 다양
- ▶ Minimal void generation
- ▶ High reliability cream
- ▶ Halogen Free, no cleaning, no chlorine and no foul smell
- ▶ Various type cream for printing and bumping



① 제품 품명(Product Name)

E F C - 3 C 0 5 - 3 0 - M

Classification by Product Form Alloy composition Powder Granularity Flux Type

인쇄용 Solder Cream (Solder Cream for printing)

품명 Product No.	솔더분류 Solder Class	솔더 성분 Solder Composition	용점(℃) Melting Point (℃)	Soldering 온도 (℃) Soldering Temp. (℃)	특징 Features
3C05	Sn-Ag System	▶Sn3Ag0.5Cu(α)	217/217	235±5	▶High reliability ▶Excellent Corrosion Resistance and Spreadability ▶ Minimum Void
5A35		▶Sn3.5(3)Ag0.5Cu (Ni, Ge)	217/217		
3A10		▶Sn1Ag0.5Cu	220/225	240±5	
3A03		▶Sn0.3Ag0.7Cu	220/227		
4B20 4I20	Sn-Ag System (Adding Bi, In)	▶Sn2.5Ag0.4Cu2Bi ▶Sn2Ag3Bi2In	215/216 195/204	230±5	▶Excellent Spreadability and Bondability ▶Possible to apply Phenol substrate
3B30	Sn-Zn System	▶Sn8Zn3Bi	191/191	220 이하	▶Possible to joining in low temperature
2B58	Sn-Bi System	▶Sn58Bi(1Ag)	139/139	220 이하	▶Possible to joining in low temperature ▶Low cost
2S50	Sn-Bi System	▶Sn5Sb	232/240	265±5	▶Possible to joining in high temperature

Dispenser용 Solder Cream (Solder Cream for Dispenser)

분류 Classification	솔더분류 Solder Class	솔더 성분 Solder Composition	용점(°C) Melting Point (°C)	특징 Features	분말입도(μm) Powder Granularity
EF Solder	EFD-2S50	Sn5Sb	232/240	▶ Good continuous printability ▶ Excellent Preservation property ▶ Minimum change of viscosity for aging time ▶ Countermeasure for high temperature	15~25μm 20~32μm 20~38μm 20~45μm
	EFD-2A35	Sn3.5Ag	217/217		
	EFD-3C05	Sn3Ag0.5Cu(α)	217/217		
	EFD-5A35	Sn3.5Ag0.5Cu(Ni,Ge)	217/217		
	EFD-3A10	Sn1Ag0.5Cu	220/225		
	EFD-3A03	Sn0.3Ag0.7Cu	220/227		
	EFD-2B58	Sn58Bi(1Ag)	139/139		

Bumping용 Solder Cream (Solder Cream for Bumping)

분류 Classification	솔더분류 Solder Class	솔더 성분 Solder Composition	용점(°C) Melting Point (°C)	특징 Features	분말입도(μm) Powder Granularity
Micro Printing Micro Dispensing	EFC-2A35-B	Sn3.5Ag	217/217	▶ Excellent continuous workability ▶ Excellent mechanical property of micro bumping soldering part ▶ Excellent reliability of micro bumping soldering part	5~20μm 5~15μm 3~7μm
	EFC-3C05-B	Sn3Ag0.5Cu(α)	217/217		
	EFC-5A35-B	Sn3.5Ag0.5Cu(Ni,Ge)	217/217		
	EFC-3A10-B	Sn1Ag0.5Cu	220/225		
	EFC-3A03-B	Sn0.3Ag0.7Cu	220/227		



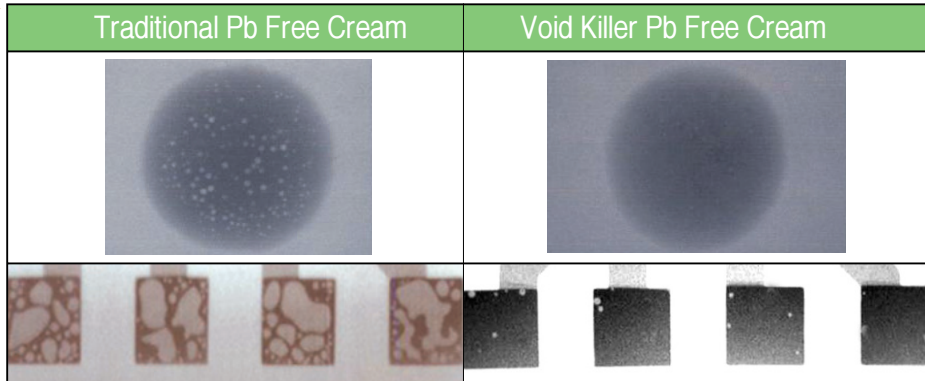
EF Solder Cream 특징 (Features of EF Solder Cream)

- ▶ Fillet Void 발생 증가
- ▶ 젖음성 부족
- ▶ Increase of Void
- ▶ Poor Wetability

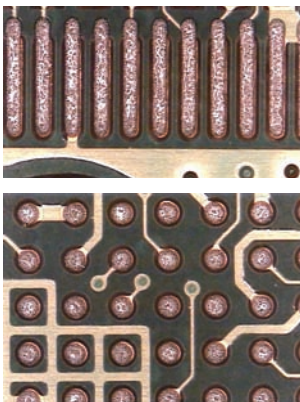
- ▶ 고순도 솔더 합금 적용
- ▶ Flux 성능 개선
- ▶ Use of Pure Solder Alloy
- ▶ Improvement of Flux

- ▶ Void Killer Cream
- ▶ Void 극소, 젖음성 향상
- ▶ Minimal Void
- ▶ Excellent Wetability

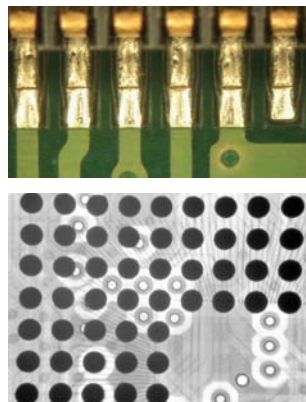
● Void 발생이 극소 (Minimal Void Generation) : Void Killer VK Series Cream



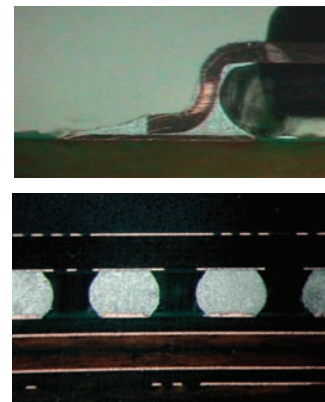
연속 작업성 및 Soldering 특성이 우수 (Excellent Continuous Workability and Soldering Property)



Printing



Soldering

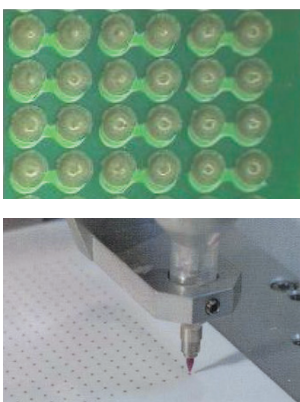


Reliability(Cross Section)

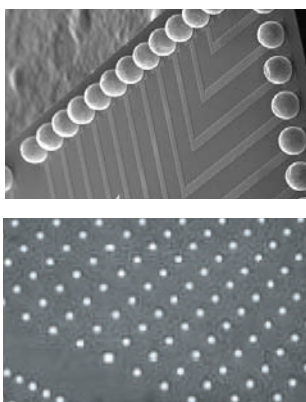
마이크로 실장용 Cream Solder의 작업성 및 Soldering 특성 (Micro Cream Solder Properties)

- ▶ 실장 한계 : 0.3mm Pitch 이하
- ▶ 솔더입자 한계 : $\phi 20\mu m$
- ▶ Limited of Printing : 0.3mm Pitch
- ▶ Powder Granularity : Above $\phi 20\mu m$

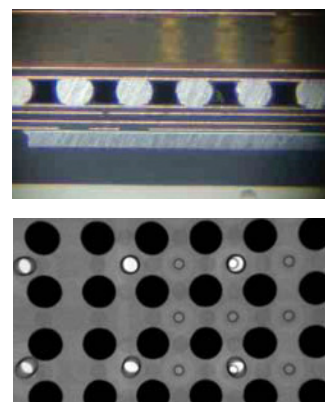
- ▶ 극미세 · Bumping 실장 가능
- ▶ $\phi 3 \sim \phi 7\mu m$ 초미세 솔더 분말
- ▶ Possible to Ultra Micro · Bumping SMT
- ▶ Ultra Micro Solder Powder Granularity : $\phi 3 \sim \phi 7\mu m$



Printing / Dispensing



Soldering / Bumping



Reliability(X-RAY / Cross Section)

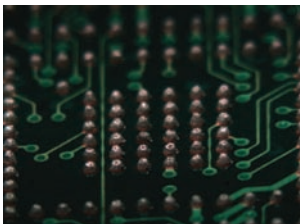
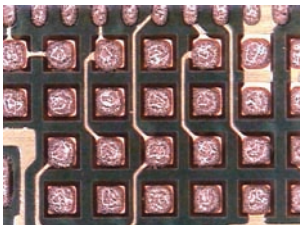
EF Solder Cream 특징 (Features of EF Solder Cream)

Silver Free Low Silver 무연솔더(Silver Free Low Silver Pb Free Solder Cream)

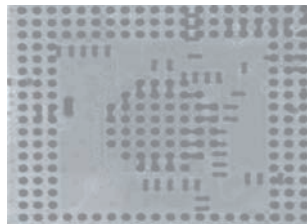
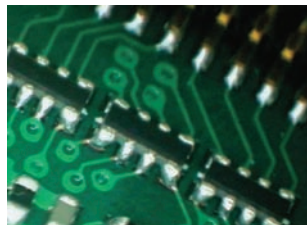
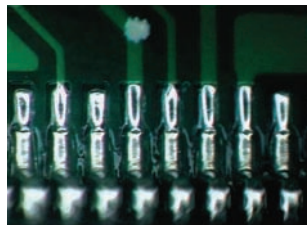
- ▶ 기존 Pb Free Solder 대비 우수한 가격 경쟁력
- ▶ 고 신뢰성
- ▶ 할로겐 프리, 무세정, 무악취
- ▶ Void 발생 극소
- ▶ 페놀PCB에 적용 가능
- ▶ Low cost than SAC305 solder
- ▶ High reliability Cream
- ▶ Cream of no cleaning, Halogen free, no foul smell
- ▶ Minimal void generation
- ▶ Possible to apply Phenol PCB

품명 Product No.	솔더분류 Solder Classification	솔더 성분 Solder Composition	용점(℃) Melting Point(℃)	Soldering 온도(℃) Soldering Temp.(℃)
3A03	Sn-Ag	▶ Sn0.3Ag0.7Cu	221/227	240±5℃
3A10		▶ Sn1.0Ag0.5Cu	221/225	

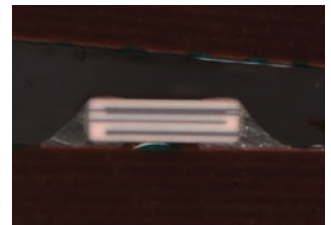
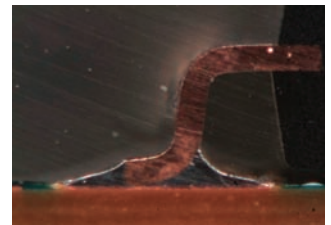
연속 작업성 및 Soldering 특성이 우수 (Excellent Continuous Workability and Soldering Property)



Printing

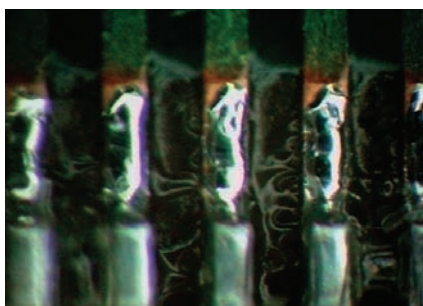


Soldering



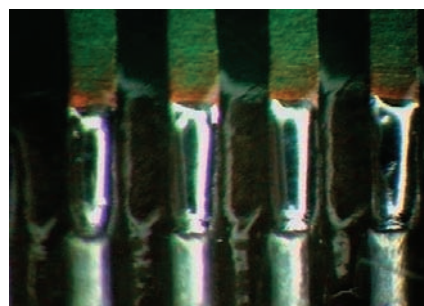
Reliability (Cross Section)

Soldering 특성 우수 및 잔사 버블 발생 없음 (Excellent Solderability and No Residue Bubble for Phenol PCB)

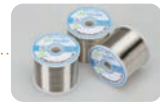


잔사 버블 발생
(Residue Bubble)

개선



잔사 및 솔더링 특성 우수
(Excellent Soldering and Residue Properties)



Pb Free EF Solder Bar Series

- ▶ 시린키지 발생 극소
- ▶ Dross 발생이 극소
- ▶ Pad 침식이 극소
- ▶ 젖음성 및 퍼짐성 특성이 우수
- ▶ 접합 신뢰성이 우수
- ▶ Minimal Shrinkage on fillet
- ▶ Minimal Dross generation
- ▶ Minimal Erosion
- ▶ Excellent wettability and Spreadability
- ▶ Superior joining Reliability

EF SOLDER BAR



● 제품 품명(Product Name)

E F B - 3 N 0 6 S

Wave용 Solder Bar (Solder Bar for Wave)

제품명 Product No.	솔더 분류 Solder Classification	솔더 성분 Solder Composition	용점(℃) Melting Point(℃)	Soldering 온도 (℃) Soldering Temperature (℃)	특 징 Features
2C07 3N06S 2N06	Sn-Cu계	▶ Sn0.7Cu(<i>α</i>) ▶ Sn0.5Cu0.06Ni(<i>α</i>) ▶ Sn0.06Ni(<i>α</i>)	227/227 220/229 230/233	260±5	▶ Minimal Dross ▶ Minimal Pad Erosion
4A03		▶ Sn0.7Cu0.3Ag(<i>α</i>)	221/227		
2S50	Sn-Sb계	▶ Sn5Sb	232/240	270±5	
3C05 2A30	Sn-Ag계	▶ Sn3Ag0.5Cu(<i>α</i>) ▶ Sn3Ag(<i>α</i>)	217/217 217/220	255±5	▶ High Reliability ▶ Minimal Dross ▶ Excellent Erosion Resistance and Spreadability
5A35		▶ Sn3.5(3)Ag0.5Cu (Ni, Ge)	217/217		

Dipping용 고온 Solder Bar (High Temperature Solder Bar for Dipping)

제품명 Product No.	솔더 성분 Solder Composition	용점(°C) Melting Point (°C)	Soldering 온도 (°C) Soldering Temperature (°C)	특징 Features
3C30	Sn3Cu(α)	227/312	350 $\pm$ 10	▶ Minimal Dross Generation ▶ Minimal Oxidant ▶ Minimal Pad Erosion ▶ Excellent Joinability
3C40	Sn4Cu(α)	227/353	390 $\pm$ 10	
4C40	Sn4Cu0.05Ni(α)	227/353	390 $\pm$ 10	

Pb Free용 산화 방지제 (Antioxidant for Pb Free)

- ▶ 용융 솔더 Dross를 극소화
- ▶ 접합 강도 향상 효과
- ▶ 젖음성 및 퍼짐성 개선
- ▶ Minimal Dross on Solder melted surface
- ▶ Improving Joining Strength
- ▶ Improvement of Wettability

제품명 Product No.	솔더 성분 Solder Composition	Soldering 온도 (°C) Soldering Temperature (°C)	용도 Use
Antiox α	Sn-Cu system	260 $\pm$ 5	Antioxidant for wave
Antiox β	Sn-Ag system	255 $\pm$ 5	
Antiox γ	Sn-Cu system	350~550	Antioxidant for dip

EF Solder Cream 특징 (Features of EF Solder Cream)

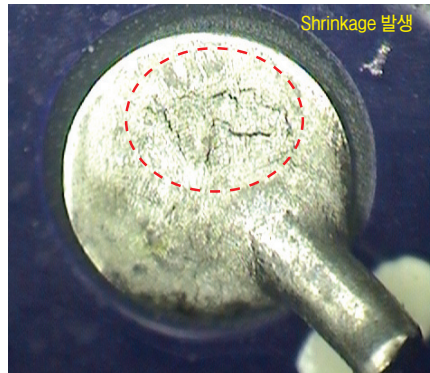
에코조인 특허제품

- ▶ Shrinkage 발생 (Sn-Ag계)
- ▶ Dross 발생 증가
- ▶ Generation of Shrinkage (Sn-Ag system)
- ▶ Increase of Dross Generation

- ▶ 에코조인 특허성분 첨가
- ▶ Shrinkage 방지제 첨가
- ▶ Dross 방지제 첨가
- ▶ Added Shrinkage Inhibitor
- ▶ Added Dross Inhibitor

- ▶ EFB Solder 전제품 Sn-Ag계 / Sn-Cu계 + (α)솔더
- ▶ 시린키지 킬러 솔더
- ▶ 드로스 킬러 솔더
- ▶ 우수한 내침식성
- ▶ 변색 방지
- ▶ ECOJOIN's EFB Solder Sn-Ag / Sn-Cu System + (α)Solder
- ▶ Product of Shrinkage Killer Solder
- ▶ Product of Dross Killer Solder
- ▶ Excellent Anti-erosion properties
- ▶ Excellent Unfading properties

Shrinkage 발생 극소(Minimal Shrinkage) : Shrinkage Killer Series Solder



Traditional Sn3Ag0.5Cu Joint



After using Shrinkage killer Solder

Dross 발생 극소(Minimal Dross) : Dross Killer Series Solder

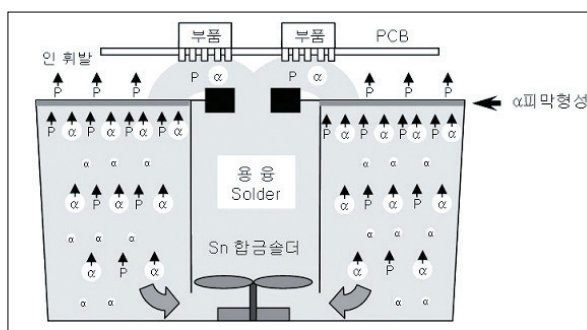


Solder Dross Generation

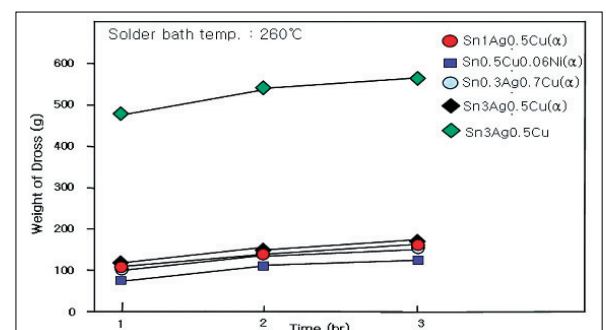


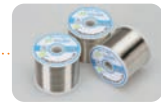
Decrease Effect of Solder Dross by Added Elements

Dross 발생 감소 원인 (Principal of Minimal Dross of Generation)



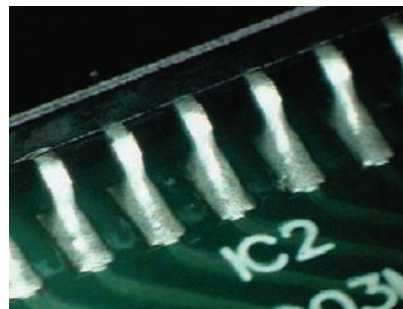
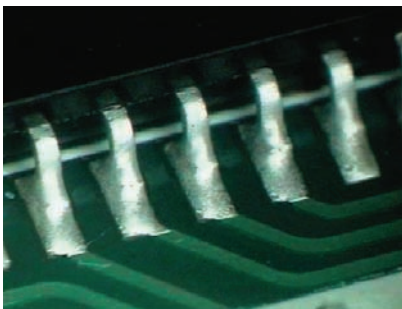
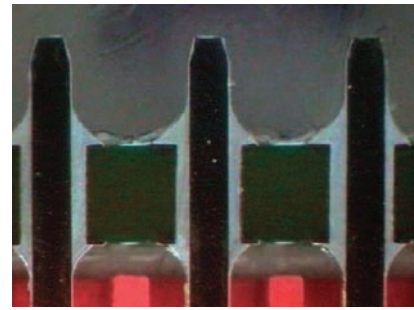
Dross 발생 감소 (Minimal Dross of Generation)





EF Solder Bar의 접합 신뢰성 (Soldering Reliability of EF Solder Bar)

열적 특성이 우수함 (Excellent Thermal Properties of soldering Joints)



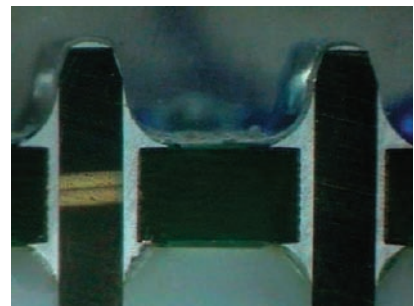
초기(Initial)

표면 (Surface)

단면분석 (Cross Section)

열충격시험 1000cycle 후 (After Thermal Shock 1000 Cycle)

Void 및 crack이 없는 양호한 Joint(Excellent Joint without void and crack defects)



Surface of Soldering Joint

Cross Section Joint

Pb Free EF Post Flux Series

① Pb Free Wave Solder용 Post Flux

- ▶ 대기중 솔더링시 솔더 흐름성 및 퍼짐성 우수
- ▶ 내열성이 우수

② Post Flux for Pb Free Wave Soldering

- ▶ Excellent Solder Flowability & Spreadability
- ▶ Excellent Thermal Resistance



Dipping용 고온 Solder Bar (High Temperature Solder Bar for Dipping)

제품명 Product No.	외관 Appearance	고형분(%) Solids (%)	비중 (Specific Gravity)	할로겐(%) Halogen (%)
EF-C20	Thin Light Yellow	14.0	0.820	0.06
EF-V85	Light Straw Color	8.5	0.818	0.035

Pb Free EF Solder Wire Series

- ▶ 동패드 및 인두팁 침식이 극소
- ▶ 퍼짐성이 우수
- ▶ 솔더 및 플럭스 비산이 극소
- ▶ 내열 및 열피로 특성이 우수
- ▶ 할로겐 프리
- ▶ Minimum erosion of copper Pad & Soldering Tip
- ▶ Excellent Spreadability
- ▶ Minimal fugacity of Solder & Flux
- ▶ Excellent Heat Resistance & Fatigue Properties
- ▶ Halogen Free

● 제품 품명(Product Name)

E F W - 5 C 0 5

EF SOLDER WIRE



Solder Wire

제품명 Product No.	솔더 성분 Solder Composition	용점(°C) Melting Point (°C)	직경(mm) Diameter(mm)	Flux 함유량(%) Flux Contents(%)	Flux활성도 Flux Activity
5C05	Sn3Ag0.5Cu(α, β)	217/218	$\phi 0.2 \sim 2.0$	2~4	RA Type RMA Type
4A03	Sn0.3Ag0.7Cu(α)	221/227			
2C07	Sn0.7Cu	227/227			
2A35	Sn3.5Ag	221/221			
4S40	Sn4Sb2.5Cu(α)	221/221			
2S50	Sn5Sb	232/240			
3A05	Sn0.5Ag0.5Cu	215/226			

* 주문생산에 의한 Glass 접합용 Sn(Zn, In) Wire Solder도 공급합니다.

제품 특성 (Product Features)

▶ Traditional Pb Free Wire

- ▶ 인두팁의 동에 의한 침식이 심함
- ▶ 젖음성이 나쁘고 비산이 많음
- ▶ 접합부의 열적 특성이 나쁨
- ▶ Erosion by copper of a soldering tip
- ▶ Inferior Wettability and Bad Fugacity
- ▶ Poor thermal properties of joining parts



▶ Pb Free EF Solder Wire by Ecojoin

- ▶ Co 성분 첨가 Solder 사용으로 해결 (5C05, 4A03 Solder)
- ▶ Solved by using Co added Solder (5C05, 4A03 Solder)



메탈리콘 솔더 (Metalicon Solder)

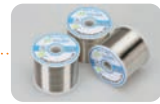
- ▶ Pb Free화에 대응하여 최근 개발된 제품으로써 콘덴서 전극용 Solder Wire 메탈리콘재를 제공하고 있습니다.
(We can Providing Metalicon Pb Free Solder for Condenser Electrode)

● 제품 품명(Product Name)

E F M - 4 Z 1 2

합금조성(Solder Alloy Composition)

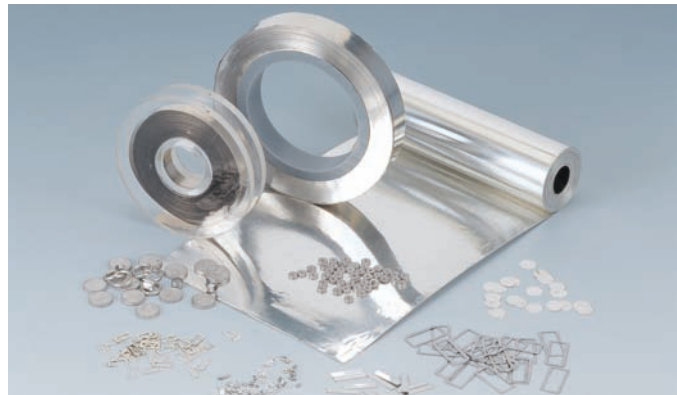
제품명 Product No.	Composition (wt%)	Temperature (°C)	Tensile Strength (N/mm ²)	Elongation (%)	Resistivity ($\mu \Omega \text{ cm}$)	Conductivity (%)
EFM-4Z12	Sn12Zn0.6Cu(α)	198.0~200.8	63.5	10.0	11.1	15.5
EFM-2Z10	Sn10Zn	199	39.58	41.1	10.8	16.0
EFM-2Z30	Sn30Zn	200~303	82.60	67.5	10.4	16.8
EFM-2Z50	Sn50Zn	200~349	14.40	44.0	7.95	21.7



Pb Free EF Solder Preform Series

- ▶ 다양한 형상 및 성분
- ▶ Roll Type 및 Preform Type
- ▶ 요구사양에 따른 주문생산
- ▶ Various types of shapes and compositions
- ▶ Roll Type and Preform Type
- ▶ Order Production for Various type

EF SOLDER Preform



제품분류 (Product Classification)

제품명 Product No.	솔더 성분 Solder Composition	용점(°C) Melting Point (°C)	형 상(Shape)			용 도(Use)
			두께(mm) Thickness(mm)	폭(mm) Width(mm)	길이(mm) Length (mm)	
2A35	Sn3.5Ag	217/218	0.05~2.0	3~200	Roll Type and Preform Type	▶ Electronic parts ▶ Semiconductor ▶ Radiator
2A10	Sn10Ag	221/290				
2A20	Sn20Ag	221/345				
2S50	Sn5Sb	232/240				
3C05	Sn3Ag0.5Cu(α)	217/217				
3A05	Sn0.5Ag0.5Cu	215/226				

Pb Free EF Solder BGA Ball Series

- ▶ ø 0.3~0.76mm까지 다양한 크기
- ▶ 진구도가 우수
- ▶ Ball의 오염도가 극소
- ▶ Various sizes from ø 0.3 to 0.76mm
- ▶ Excellent Spherical Shape
- ▶ Minimum Ball Pollution

EF SOLDER BALL



제품분류 (Product Classification)

제품명 Product No.	합금조성 Alloy Composition	용융온도(°C) (Melting Temperature)		규격(Size)
		고 상(Solid)	액 상(Liquid)	
EFG-2A35	Sn3.5Ag	221	221	ø0.3~0.76mm (±5~20μm)
EFG-5C05	Sn3Ag0.5Cu(α)	217	217	
5C05EFG-5A35	Sn3.5Ag0.5Cu(Ni, Ge)	217	217	

Tack Flux for EF Solder Ball Array

- ① Bumping용 Tack Flux
 - ▶ Tack 및 작업성 특성이 우수
 - ▶ Halogen Free Flux
- ② Tack Flux for Bumping
 - ▶ Excellent Tack & workability Property
 - ▶ Halogen Free Flux

제품명 Product No.	점 도(Pas) Viscosity (Pas)	점착성(gf) Adhesion (gf)	할로겐(%) Halogen (%)	종 류 Types
EF-Tack1	15~40	120~180	Below 0.1	No cleaning/ Cleaning
EF-Tack2	15~40	120~180	0	

EF Conductive Paste Series(신제품)

- ▶ 저온 접합 가능
 - ▶ 기존 SMT 라인 사용 가능
 - ▶ 우수한 작업 특성
 - ▶ 높은 접속저항 특성
- ▶ Possible to low temperature joining
 - ▶ Possible to apply established SMT Line
 - ▶ Excellent workability (Printing, Dispensing properties)
 - ▶ High contact resistance properties

① 제품 품명(Product Name)

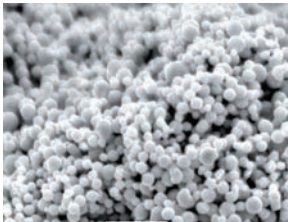
E F C P - A g 1

EF Paste Conductive Paste

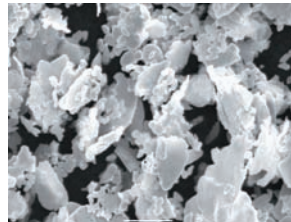


품명 Product No.	분류 Classification	경화온도(℃) Curing Point(℃)	경화시간 Curing Time(sec)
EFCP-Ag1	Ag	150℃	180 sec
EFCP-AgCu1	Ag-Cu		

고정정 극미세 분말 및 Flake 적용

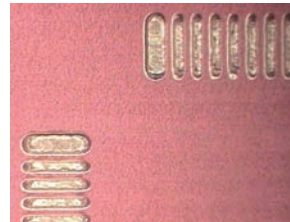


Powder

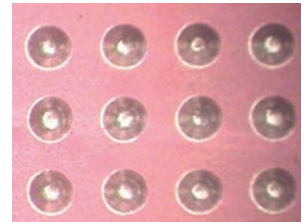


Flake

우수한 작업 특성

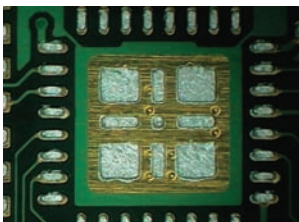
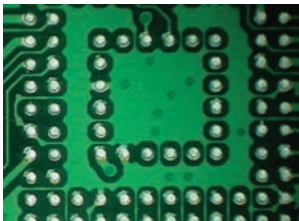
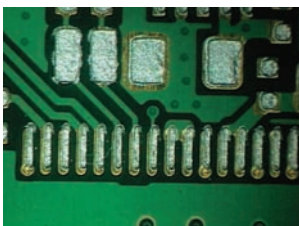


Printing

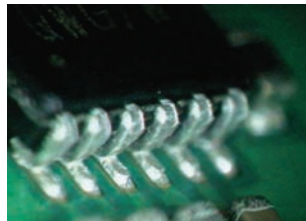
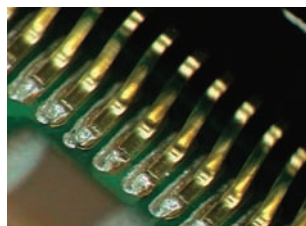


Dispensing

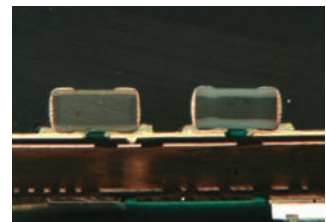
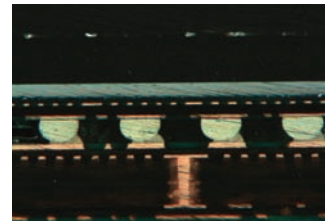
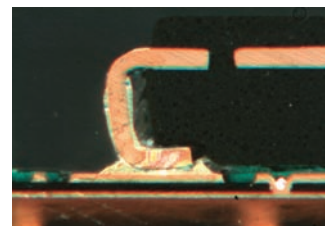
Mobile Phone 적용 예 (Application of Conductive paste for Mobile Phone)



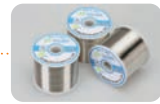
Printing



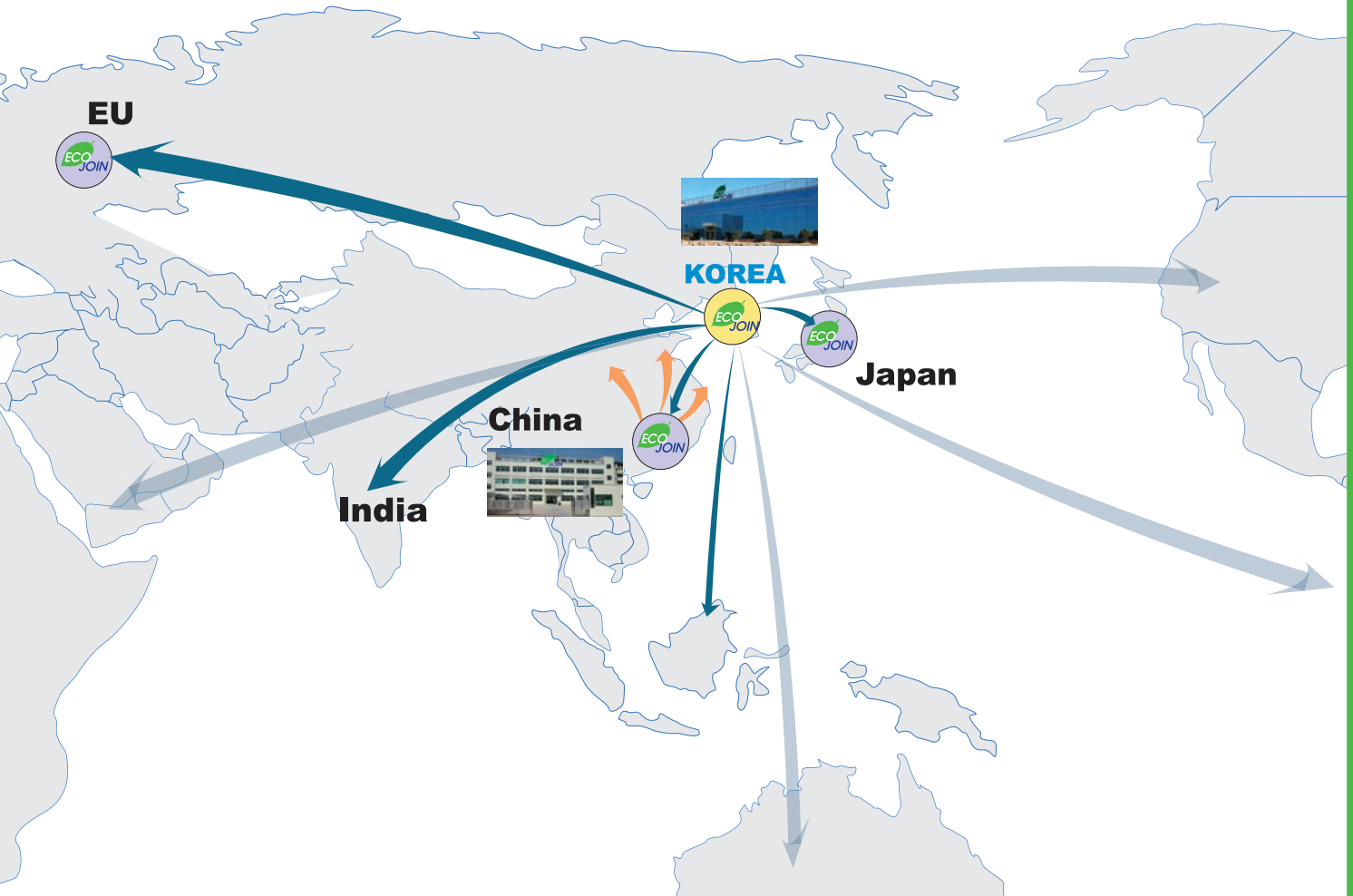
Curing



Reliability (Cross Section)



ECOJOIN GLOBAL SALES NETWORK



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